

Sampling



Provides lot-based sampling as well as sub-material sampling at metrology steps

Overview

In many cases it's not practical to inspect or measure every single lot; and even in an inspection or metrology step, it's not practical to inspect or measure every single unit of a lot. The Sampling module provides the capability to implement sampling strategies by pre-defining 1) which materials must

go through an inspection or metrology step based on time or counters; and 2) which sub-materials to be measured at an inspection or metrology step. Once the sampling strategy is defined, the system will execute and enforce it automatically.

The screenshot displays a user interface for configuring a sampling plan. The main section is titled 'My Sampling Plan (Active)' and is divided into 'DETAILS' and 'CONTEXT' sections.

DETAILS:

- Sampling Plan:** Name: My Sampling Plan, Description: My Sampling Plan, Type: Standard, Universal State: Active.
- Details:** Type: CounterBased, Counter Frequency: 10.

CONTEXT:

Context Information (1)

ORDER	NAME	DESCRIPTION	CONTEXT
1	Resource	Resource	MaterialResource

At the bottom of the interface, there is a search bar and pagination controls showing 'Rows per page: 10' and 'Page 1 of 1 (1 records)'.

Figure 1 Sampling Plan example

Key Features

- Support for static and dynamic inspection plans, including AQL, supporting:
 - In-process measurements as well as measurements that are performed in different inspection stations (e.g.: a lab)
 - Variable and Attribute results
 - The definition and capture of measurement instruments, ensuring that they are calibrated and that they cover the required range and have the required precision
 - Automatic severity switching rules
- Support for lot-based sampling strategies based on flexible contexts that can be:
 - Counter based (e.g.: every 10th lot of a certain product)
 - Time based (e.g.: one lot from a certain equipment every 8 hours)
- Support for sub-material selection at a metrology step, for example to measure the top, middle and bottom wafers and in that particular sequence. The sub-materials to be measured can be defined manually or by a business rule (system or user-defined).
- Integration with Material Tracking and transparent to the user.

Benefits

- Improved process control
- Reduction of costs
- Reduction in the opportunity for errors

✔ Post Data to Data Collection


■ LOT-01 (InProcess) / 🏭 MOSRM8HQ (MOSRM8HQ Product) / ● Inspection / 100 Kg

< Width (Variable)

WIDTH (VARIABLE)	
* Sample 1	999 mm
* Sample 2	999.8 mm
* Sample 3	1000.1 mm
* Sample 4	998.8 mm
* Sample 5	1000.4 mm

Last entered value: Width > Sample 5 > 1000.4 mm

Measure the width of the scalpel at the thinnest point.



Width > Sample 5

999	1,000	1,001	
1000.4 mm			
7	8	9	C
4	5	6	Del
1	2	3	OK
+/-	0	.	

Comments:

Cancel
Post

Figure 2 Inspection example